

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Ting Cheong Ang	05/30/2007
RECEIVING PARTY DATA	
Name:	Semiconductor Manufacturing International (Shanghai) Corporation
Street Address:	18 Zhang Jiang Road, Pudong New Area
City:	Shanghai
State/Country:	CHINA
Postal Code:	201203
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11539612
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NAME OF SUBMITTER:	Richard T. Ogawa
Total Attachments: 1 source=021653-012500US ASSIGNMENT#page1.tif	

CH \$40.00 11539612

ASSIGNMENT OF PATENT APPLICATION

SOLE

WHEREAS, **Ting Cheong Ang** of 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203 People's Republic of China, hereinafter referred to as "Assignor," is the inventor of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: **METHOD WITH HIGH GAPFILL CAPABILITY FOR SEMICONDUCTOR DEVICES**

Date(s) of execution of Declaration:

Filing Date: October 6, 2006

Application No.: 11/539,612; and

WHEREAS, **Semiconductor Manufacturing International (Shanghai) Corporation**, a corporation of People's Republic of China, located at 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has assigned, and by these presents does assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on any patent application claiming priority from the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignor had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees that Assignor will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignor hereby authorizes and requests Townsend and Townsend and Crew LLP, Two Embarcadero Center, Eighth Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignor has signed his/her name on the date indicated.

Dated: 30th May 2007



Ting Cheong Ang

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